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DOCKET NO. 00-282
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In the Claims:

Claim 1 (currently amended): A method for insulating a bonding wire comprising ~~[the following]~~ steps of:

- (a) attaching a bonding wire to a bond pad; ~~[and]~~
- (b) moving a dispensing tool from a non-coating position to a coating position;
- (c) partially surrounding the bonding wire in the coating position by a nozzle orifice having an arcuate shape in a dimension perpendicular to the bonding wire; and
- (d) dispensing an insulating liquid from the nozzle orifice to coat ~~[(b) coating]~~ the bonding wire with an insulating liquid while drawing the bonding wire through a bond tool from the bond pad to a package lead.

Claim 2 (currently amended): The method of claim 1 further comprising after step (d) ~~[(b)]~~ the step of ceasing to coat the bonding wire with the insulating liquid.

Claim 3 (currently amended): The method of claim 1 further comprising after step (d) ~~[(b)]~~ the step of attaching the bonding wire to the package lead.

Claim 4 (currently amended): The method of claim 1 further comprising after step (d) ~~[(b)]~~ the step of solidifying the insulating liquid coating the bonding wire.

Claim 5 (original): The method of claim 4 wherein the step of solidifying the insulating liquid comprises one of heating the bonding wire and exposing the bonding wire to ultraviolet radiation.

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Claims 6-11 (previously withdrawn)

Claim 12 (currently amended): A method for insulating a bonding wire comprising ~~[the following]~~ steps of:

- (a) attaching a bonding wire to a bond pad with a bond tool;
- (b) moving a dispensing tool from a non-coating position to a coating position;
- (c) partially surrounding the bonding wire in the coating position by a nozzle orifice having an arcuate shape in a dimension perpendicular to the bonding wire;
- (d) [-(b)-] pumping an insulating liquid through the [a] nozzle orifice [coupled to the bond tool] to apply a uniform thickness of the insulating liquid on the bonding wire; and
- (e) [-(c)-] drawing the bonding wire through the bond tool from the bond pad toward a package lead while pumping the insulating liquid.

Claim 13 (previously added): The method of Claim 12 further comprising the step of ceasing to pump the insulating liquid.

Claim 14 (previously added): The method of Claim 13 further comprising the step of attaching the bonding wire to the package lead after ceasing to pump the insulating liquid.

Claim 15 (previously added): The method of Claim 14 further comprising the step of solidifying the insulating liquid on the bonding wire after attaching the bonding wire to the package lead.

Claim 16 (previously added): The method of Claim 15

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wherein the step of solidifying the insulating liquid comprises one of heating the bonding wire and exposing the bonding wire to ultraviolet radiation.

Claim 17 (currently amended): The method of Claim 12 further comprising repeating steps (a), (b), ~~[and]~~ (c), (d) and (e) to complete a microelectronic package.

Claim 18 (new): The method of Claim 12 wherein step (c) comprises partially surrounding the bonding wire in the coating position by a nozzle orifice having a dimension parallel to the bonding wire that is relatively narrow with respect to a dimension of the nozzle orifice perpendicular to the bonding wire.

Claim 19 (new): The method of Claim 18 comprising partially surrounding the bonding wire in the coating position by a nozzle orifice having a dimension parallel to the bonding wire of about 50 microns and a dimension perpendicular to the bonding wire of about 100 microns.

Claim 20 (new): The method of Claim 1 comprising partially surrounding the bonding wire in the coating position by a nozzle orifice having a dimension parallel to the bonding wire of about 50 microns and a dimension perpendicular to the bonding wire of about 100 microns.